

AMENDMENTS

In the Claims

Please cancel claims 6-8 and 25 without any disclaimer or a prejudice to.

REMARKS

Reconsideration of this Application is respectfully requested in light of the following remarks. Claims 1, 3-5 and 9-12 are now currently active in this application, of which claims 1 and 9 are independent.

In the advisory action mailed on April 10, 2003, the Examiner allowed claims 1, 3-5 and 9-12. By this amendment, rejected claims 6-8 and 25 have been canceled. Thus, it is respectfully requested that the present application with pending claims 1, 3-5 and 9-12 be issued.

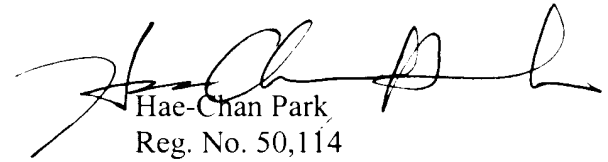
A list of pending claims is attached herewith as **Appendix A**.

CONCLUSION

All of the stated grounds of objection and rejection have been properly traversed, accommodated, or rendered moot. Applicants therefore respectfully request that the Examiner reconsider all presently outstanding objections and rejections and that they be withdrawn. Applicants believe that a full and complete response has been made to the outstanding Office Action and, as such, claims 1, 3-5 and 9-12 are in condition for allowance or, in the alternative, in a better form for appeal. If the Examiner believes, for any reason, that personal communication will expedite prosecution of this application, the Examiner is invited to telephone the undersigned at the number provided.

Prompt and favorable consideration of this Amendment is respectfully requested.

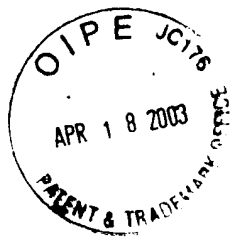
Respectfully submitted,



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APPENDIX A

1. (Previously Amended) An organic EL device, comprising:
a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT with a conductive interface pad connected thereto and a capacitor formed on the first insulating substrate; and
an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode,
wherein the conductive interface pad is directly connected to the metal electrode.
3. (Presiously Amended) The device of claim 1, wherein the organic EL substrate further includes a protection film that prevents external oxygen and moisture from permeating.
4. The device of claim 3, wherein the protection film is formed by depositing a SiNx layer and a SiO₂ layer at least once.
5. The device of claim 4, wherein the TFT array substrate and the organic EL substate are sealed by a UV-curable agent.
9. (Previously Amended) An organic EL device, comprising:
a thin film transistor (TFT) array substrate including a first insulating substrate, a TFT, a capacitor formed on the first insulating substrate, a conductive interface pad and a conductive bump pad formed on the conductive interface pad; and

an organic EL substrate including a second insulating substrate, a transparent electrode, an organic EL layer and a metal electrode, and a polymer bump,

wherein the conductive bump pad contacts a portion of the metal electrode corresponding to the polymer bump by a conductive bonding agent, and

wherein the TFT is electrically connected to the metal electrode.

10. The device of claim 9, wherein the conductive bonding agent is an anisotropic conductive film (ACF).

11. (Previously Amended) The device of claim 10, wherein the anisotropic conductive film prevents oxygen and moisture from permeating through the second insulating substrate.

12. The device of claim 1, wherein the transparent electrode, the organic EL layer and the metal electrode are sequentially stacked on the second insulating layer.